TOSHIBA Field Effect Transistor Silicon N Channel MOS Type

SSM6N37FU

- High Speed Switching Applications
- Analog Switch Applications

Unit: mm

_	- 1	.5V	<i>'</i> ~	riv	10
•		. i) V	. (1	111	/

•	Low ON-resistance	$R_{DS(ON)} = 5.60 \Omega \text{ (max) } (@V_{GS} = 1.5 \text{ V})$
	LOW OIL TOOISIATION	1103(0)(1) 0.00 12 (110)((@ 103 1.0 1)

 $R_{DS(ON)} = 4.05 \Omega \text{ (max) (@V_{GS} = 1.8 V)}$

 $R_{DS(ON)} = 3.02 \Omega \text{ (max) } (@V_{GS} = 2.5 \text{ V})$

 $R_{DS(ON)} = 2.20 \Omega \text{ (max) } (@V_{GS} = 4.5 \text{ V})$

Absolute Maximum Ratings (Ta = 25°C)

(Q1, Q2 Common)

Characteristics		Symbol	Rating	Unit	
Drain-Source voltage		V_{DSS}	20	V	
Gate-Source voltage		V_{GSS}	± 10	V	
Drain current	DC	I _D	250	mA	
Diam current	Pulse	I _{DP}	500		
Power dissipation		P _D (Note1)	300	mW	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55 to 150	°C	

1. SOURCE 1 4. SOURCE 2
2. GATE 1 5. GATE 2
3. DRAIN 2 6. DRAIN 1

US6

JEDEC —

JEITA —

TOSHIBA 2-2J1C

2.1 ± 0.1

Weight: 6.8 mg(typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the

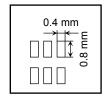
reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Total rating

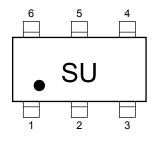
Mounted on FR4 board

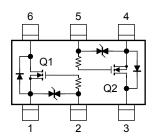
 $(25.4 \text{ mm} \times 25.4 \text{ mm} \times 1.6 \text{ mm}, \text{ Cu Pad: } 0.32 \text{mm}^2 \times 6)$



Marking(top view)

Equivalent Circuit (top view)





Start of commercial production 2010-11

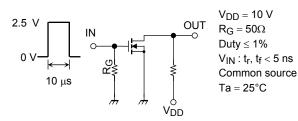
Electrical Characteristics (Ta = 25°C) (Q1, Q2 Common)

Chara	acteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain-source breakdown voltage		V _{(BR) DSS}	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	20	_	_	V
		V (BR) DSX	I _D = 1 mA, V _{GS} = -10 V	12	_	_	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Drain cut-off current		I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V	_	_	1	μА
Gate leakage curre	ent	I _{GSS}	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±1	μА
Gate threshold voltage		V _{th}	$V_{DS} = 3 \text{ V}, I_D = 1 \text{ mA}$	0.35	_	1.0	V
Forward transfer admittance		Y _{fs}	$V_{DS} = 3 \text{ V}, I_D = 100 \text{ mA}$ (Note2)	0.14	0.28	_	S
Drain-source ON-resistance		R _{DS (ON)}	$I_D = 100 \text{ mA}, V_{GS} = 4.5 \text{ V}$ (Note2)	_	1.65	2.20	Ω
			$I_D = 50 \text{ mA}, V_{GS} = 2.5 \text{ V}$ (Note2)	_	2.16	3.02	
			$I_D = 20 \text{ mA}, V_{GS} = 1.8 \text{ V}$ (Note2)	_	2.66	4.05	
			$I_D = 10 \text{ mA}, V_{GS} = 1.5 \text{ V}$ (Note2)	_	3.07	5.60	
Input capacitance		C _{iss}		_	12	_	
Output capacitance		Coss	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	5.5	_	pF
Reverse transfer capacitance		C _{rss}		—	4.1	_	
Switching time	Turn-on time	t _{on}	V _{DD} = 10 V, I _D = 100 mA	_	18	_	ns
	Turn-off time	t _{off}	V_{GS} = 0 to 2.5 V, R_G = 50 Ω	_	36	_	
Drain-Source forward voltage		V _{DSF}	$I_D = -250 \text{ mA}, V_{GS} = 0 \text{ V}$ (Note2)	_	-0.9	-1.2	٧

Note2: Pulse test

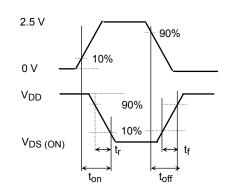
Switching Time Test Circuit





(b) V_{IN}

(c) V_{OUT}



Precaution

Let V_{th} be the voltage applied between gate and source that causes the drain current (I_D) to be low (1mA for the SSM6N37FU). Then, for normal switching operation, $V_{GS(on)}$ must be higher than V_{th} , and $V_{GS(off)}$ must be lower than V_{th} . This relationship can be expressed as: $V_{GS(off)} < V_{th} < V_{GS(on)}$.

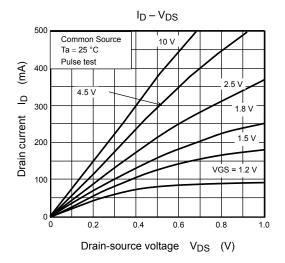
Take this into consideration when using the device.

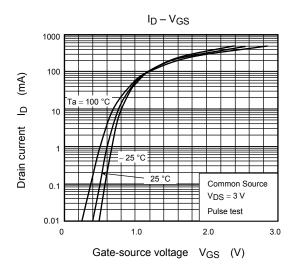
Handling Precaution

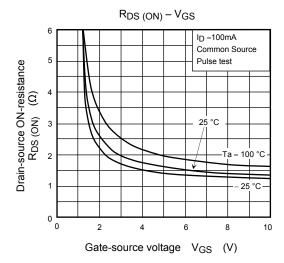
When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.

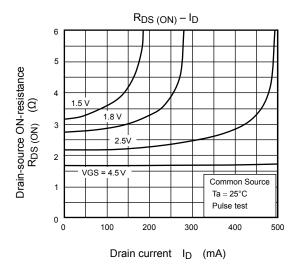
Thermal resistance $R_{th\ (ch-a)}$ and power dissipation P_D vary depending on board material, board area, board thickness and pad area. When using this device, please take heat dissipation into consideration

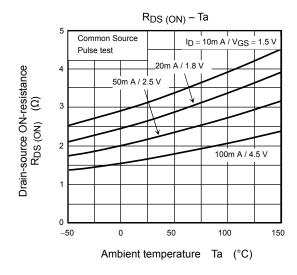
(Q1, Q2 Common)

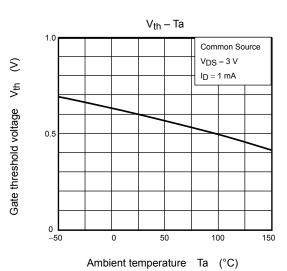


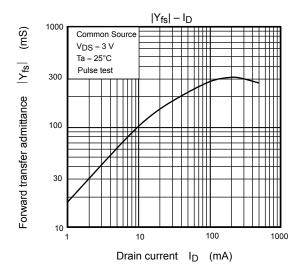


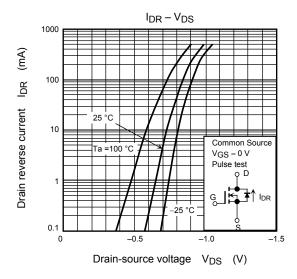


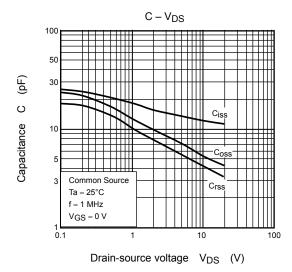


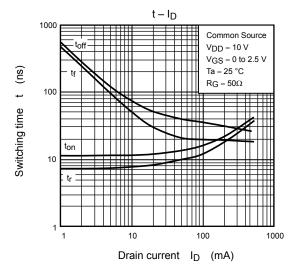


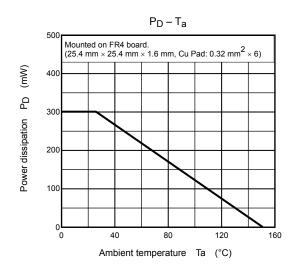












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